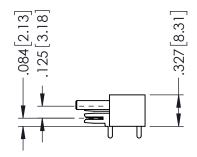




- .200 (5.08) Contact Spacing x .300 (7.62) Row Spacing with Staggered Grid
- Mounts onto .062 (1.57) or .093 (2.36) Nominal Thickness P.C. Board by Soldering and/or Staking of P.C. Tails
- Edacon Hermaphroditic Contact Mating Design
- Mounting Hole and Guide Pin Options
- 421 Series Designed to Mate with Non-Card Guide Versions of 408 or 415 Series, 422 Series Designed to Mate with Card Guide Versions of 408 or 415 Series, 423 Series Designed to Mate with 424 or 438 Series



ORIGINAL



## **Specifications**

- Insulator Material: Polyphenylene Sulphide, UL 94V-0, Colour: Green
- Contact Material: Phosphor Bronze Alloy CA-510
- Contact Plating: Gold over Nickel for Entire Contact
- Current Rating: 10 Amperes
- Contact Resistance: 10 Milliohms Maximum
- Dielectric Withstanding Voltage: 2000 V AC rms at Sea Level
- Insulation Resistance: 5000 Megohms Minimum
- Operating Temperature: -65 to +125 Degrees C
- Insertion and Withstanding Force: 2 to 16 oz (0.56 to 4.45 N) per Contact Position

	421/422/423 Series High Reliability Interlock Connector			ACAD REFERENCE NO. 421 -ENG-MASTER			
- 1	PART NUMBER: 423-017-520-102		DRAWN:	J.LEE	DATE: A	UG. 27/09	
			CHECKED:		DATE:		
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			421	-ENG-MASTE	R	1	